

Octal D Flip-Flop with Enable

The SN74LS377 is an 8-bit register built using advanced Low Power Schottky technology. This register consists of eight D-type flip-flops with a buffered common clock and a buffered common clock enable.

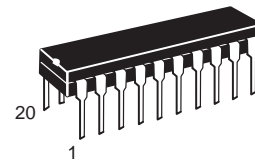
- 8-Bit High Speed Parallel Registers
- Positive Edge-Triggered D-Type Flip Flops
- Fully Buffered Common Clock and Enable Inputs
- True and Complement Outputs
- Input Clamp Diodes Limit High Speed Termination Effects

GUARANTEED OPERATING RANGES

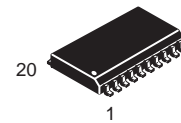
Symbol	Parameter	Min	Typ	Max	Unit
V _{CC}	Supply Voltage	4.75	5.0	5.25	V
T _A	Operating Ambient Temperature Range	0	25	70	°C
I _{OH}	Output Current – High			-0.4	mA
I _{OL}	Output Current – Low			8.0	mA

74LS377

**LOW
POWER
SCHOTTKY**



**PLASTIC
N SUFFIX
CASE 738**

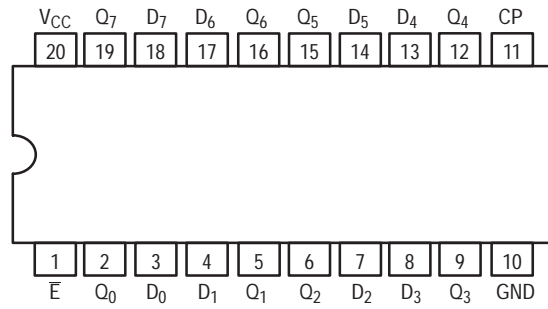


**SOIC
DW SUFFIX
CASE 751D**

ORDERING INFORMATION

Device	Package	
SN74LS377N	16 Pin DIP	
SN74LS377DW	16 Pin	

CONNECTION DIAGRAM DIP (TOP VIEW)



NOTE:
The Flatpak version
has the same pinouts
(Connection Diagram) as
the Dual In-Line Package.

PIN NAMES

\bar{E}	Enable (Active LOW) Input
$D_0 - D_3$	Data Inputs
CP	Clock (Active HIGH Going Edge) Input
$Q_0 - Q_3$	True Outputs
$\bar{Q}_0 - \bar{Q}_3$	Complemented Outputs

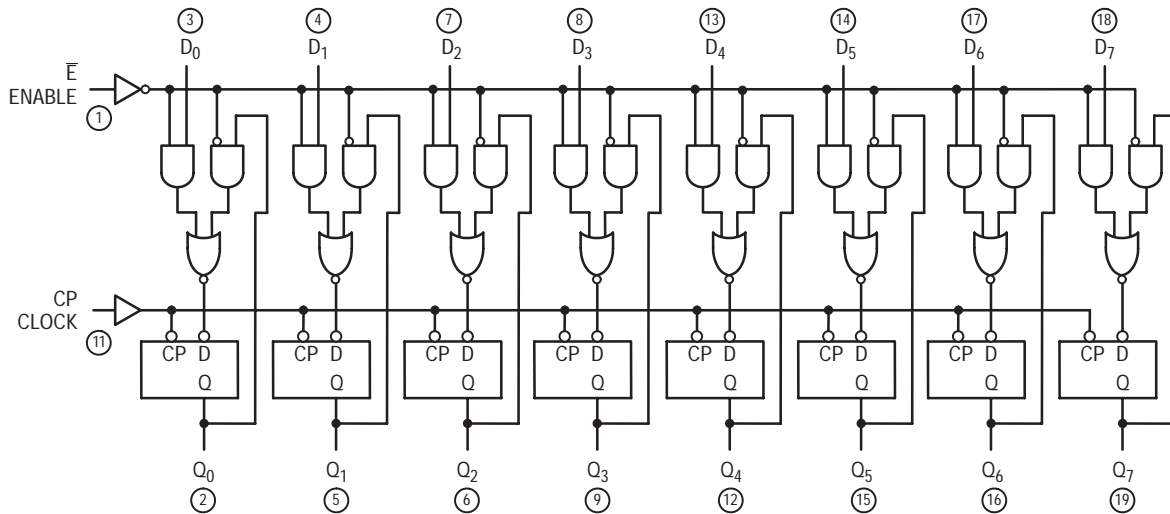
LOADING (Note a)

	HIGH	LOW
\bar{E}	0.5 U.L.	0.25 U.L.
$D_0 - D_3$	0.5 U.L.	0.25 U.L.
CP	0.5 U.L.	0.25 U.L.
$Q_0 - Q_3$	10 U.L.	5 U.L.
$\bar{Q}_0 - \bar{Q}_3$	10 U.L.	5 U.L.

NOTES:

a) 1 TTL Unit Load (U.L.) = 40 μ A HIGH/1.6 mA LOW.

LOGIC DIAGRAM



DC CHARACTERISTICS OVER OPERATING TEMPERATURE RANGE (unless otherwise specified)

Symbol	Parameter	Limits			Unit	Test Conditions
		Min	Typ	Max		
V _{IH}	Input HIGH Voltage	2.0			V	Guaranteed Input HIGH Voltage for All Inputs
V _{IL}	Input LOW Voltage			0.8	V	Guaranteed Input LOW Voltage for All Inputs
V _{IK}	Input Clamp Diode Voltage		-0.65	-1.5	V	V _{CC} = MIN, I _{IN} = -18 mA
V _{OH}	Output HIGH Voltage	2.7	3.5		V	V _{CC} = MIN, I _{OH} = MAX, V _{IN} = V _{IH} or V _{IL} per Truth Table
V _{OL}	Output LOW Voltage		0.25	0.4	V	I _{OL} = 4.0 mA V _{CC} = V _{CC} MIN, V _{IN} = V _{IL} or V _{IH} per Truth Table
			0.35	0.5	V	
I _{IH}	Input HIGH Current			20	μA	V _{CC} = MAX, V _{IN} = 2.7 V
				0.1	mA	V _{CC} = MAX, V _{IN} = 7.0 V
I _{IL}	Input LOW Current			-0.4	mA	V _{CC} = MAX, V _{IN} = 0.4 V
I _{OS}	Short Circuit Current (Note 1)	-20		-100	mA	V _{CC} = MAX
I _{CC}	Power Supply Current			28	mA	V _{CC} = MAX, NOTE 1

NOTE: With all inputs open and GND applied to all data and enable inputs, I_{CC} is measured after a momentary GND, then 4.5 V is applied to clock.
Note 1: Not more than one output should be shorted at a time, nor for more than 1 second.

AC CHARACTERISTICS (T_A = 25°C, V_{CC} = 5.0 V)

Symbol	Parameter	Limits			Unit	Test Conditions
		Min	Typ	Max		
f _{MAX}	Maximum Clock Frequency	30	40		MHz	V _{CC} = 5.0 V C _L = 15 pF
t _{PLH} t _{PHL}	Propagation Delay, Clock to Output		17 18	27 27	ns	

AC SETUP REQUIREMENTS (T_A = 25°C, V_{CC} = 5.0 V)

Symbol	Parameter		Limits			Unit	Test Conditions
			Min	Typ	Max		
t _W	Any Pulse Width		20			ns	V _{CC} = 5.0 V
t _s	Data Setup Time		20			ns	
t _s	Enable Setup Time	Inactive — State	10			ns	
		Active — State	25			ns	
t _h	Any Hold Time		5.0			ns	




DEFINITION OF TERMS

SETUP TIME (t_s) — is defined as the minimum time required for the correct logic level to be present at the logic input prior to the clock transition from LOW-to-HIGH in order to be recognized and transferred to the outputs.

HOLD TIME (t_h) — is defined as the minimum time following the clock transition from LOW-to-HIGH that the

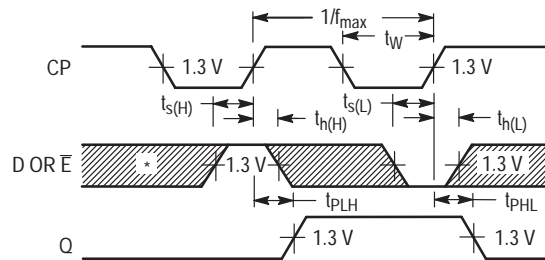
logic level must be maintained at the input in order to ensure continued recognition. A negative HOLD TIME indicates that the correct logic level may be released prior to the clock transition from LOW-to-HIGH and still be recognized.

TRUTH TABLE

\bar{E}	CP	D_n	Q_n	\bar{Q}_n
H		X	No Change	No Change
L		H	H	L
L		L	L	H

L = LOW Voltage Level
H = HIGH Voltage Level
X = Immaterial

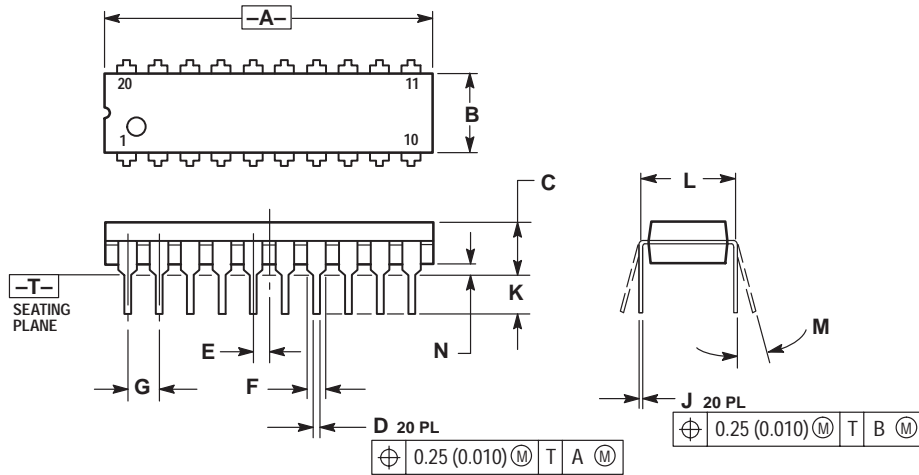
AC WAVEFORM



*The shaded areas indicate when the input is permitted to change for predictable output performance.

PACKAGE DIMENSIONS

N SUFFIX PLASTIC PACKAGE CASE 738-03 ISSUE E

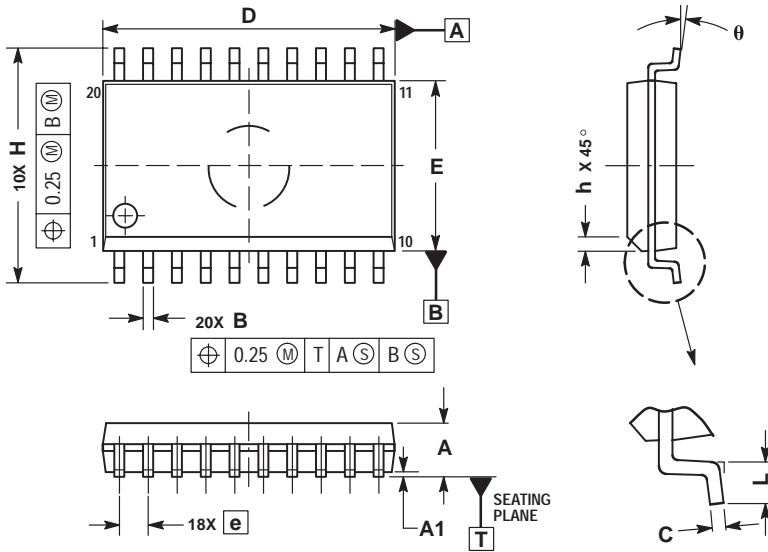


- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.
 3. DIMENSION L TO CENTER OF LEAD WHEN FORMED PARALLEL.
 4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	1.010	1.070	25.66	27.17
B	0.240	0.260	6.10	6.60
C	0.150	0.180	3.81	4.57
D	0.015	0.022	0.39	0.55
E	0.050 BSC		1.27 BSC	
F	0.050	0.070	1.27	1.77
G	0.100 BSC		2.54 BSC	
J	0.008	0.015	0.21	0.38
K	0.110	0.140	2.80	3.55
L	0.300 BSC		7.62 BSC	
M	0°	15°	0°	15°
N	0.020	0.040	0.51	1.01

PACKAGE DIMENSIONS

D SUFFIX PLASTIC SOIC PACKAGE CASE 751D-05 ISSUE F



NOTES:

1. DIMENSIONS ARE IN MILLIMETERS.
2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994.
3. DIMENSIONS D AND E DO NOT INCLUDE MOLD PROTRUSION.
4. MAXIMUM MOLD PROTRUSION 0.15 PER SIDE.
5. DIMENSION B DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.13 TOTAL IN EXCESS OF B DIMENSION AT MAXIMUM MATERIAL CONDITION.

DIM	MILLIMETERS	
	MIN	MAX
A	2.35	2.65
A1	0.10	0.25
B	0.35	0.49
C	0.23	0.32
D	12.65	12.95
E	7.40	7.60
e	1.27 BSC	
H	10.05	10.55
h	0.25	0.75
L	0.50	0.90
theta	0°	7°